



Press Release

Infineon Introduces DrBlade, the New Generation DrMOS in Innovative Chip-Embedded Packaging Technology

Neubiberg, Germany and Long Beach, CA (USA) – March 18, 2013 – Today at the Applied Power Electronics Conference & Exposition (APEC) 2013, Infineon Technologies AG (FSE: IFX / OTCQX:IFNNY) introduced [DrBlade](#) – the first integrated DC/DC driver and MOSFET VR power stage implemented in an innovative chip-embedded package technology. DrBlade contains the latest generation low voltage DC/DC driver technology and [OptiMOS™](#) MOSFET devices. The MOSFET technology features lowest area specific resistance and application specific optimized Figures of Merit to achieve highest efficiency in DC/DC voltage regulation systems for computing and telecom, including Blade and Rack servers, PC-motherboards, notebooks and game consoles.

New Blade packaging technology

Infineon's highly innovative [Blade](#) packaging technology is based on chip embedding concepts. Standard packaging processes like wire or clip bonding, as well as common molding techniques, are replaced with galvanic processes. The die also is protected by a laminate foil. The results are a significantly reduced package footprint, package resistance and inductance, as well as low thermal resistance.

“Infineon is the first semiconductor company to introduce an integrated driver and MOSFET halfbridge in Blade technology. DrBlade is another proof of our leading role in power semiconductors, making server applications highly efficient over the whole load range,” said Richard Kuncic, Senior Director Low Voltage Power Conversion at Infineon Technologies.

Saving space and gaining efficiency

The DrBlade package measures 5x5mm and has a low profile of 0.5mm, fulfilling demand for higher power density and space saving in computing systems. Due to the optimized pin assignment DrBlade enables a simplified PCB layout. The new

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chip-embedded packaging technology in combination with OptiMOS MOSFETs by Infineon makes DrBlade the best solution for voltage regulators in the low-voltage segment.

Availability & Pricing

Samples of DrBlade are now available, with production devices available in the second quarter of 2013.

For additional information on Infineon's new Blade family please visit www.infineon.com/drblade.

About Infineon

[Infineon](http://www.infineon.com) Technologies AG, Neubiberg, Germany, offers semiconductor and system solutions addressing three central challenges to modern society: [energy efficiency](#), [mobility](#), and [security](#). In the 2012 fiscal year (ending September 30), the Company reported sales of Euro 3.9 billion with close to 26,700 employees worldwide. Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the over-the-counter market OTCQX International Premier (ticker symbol: IFNNY).

Further information is available at www.infineon.com

This news release is available online at www.infineon.com/press

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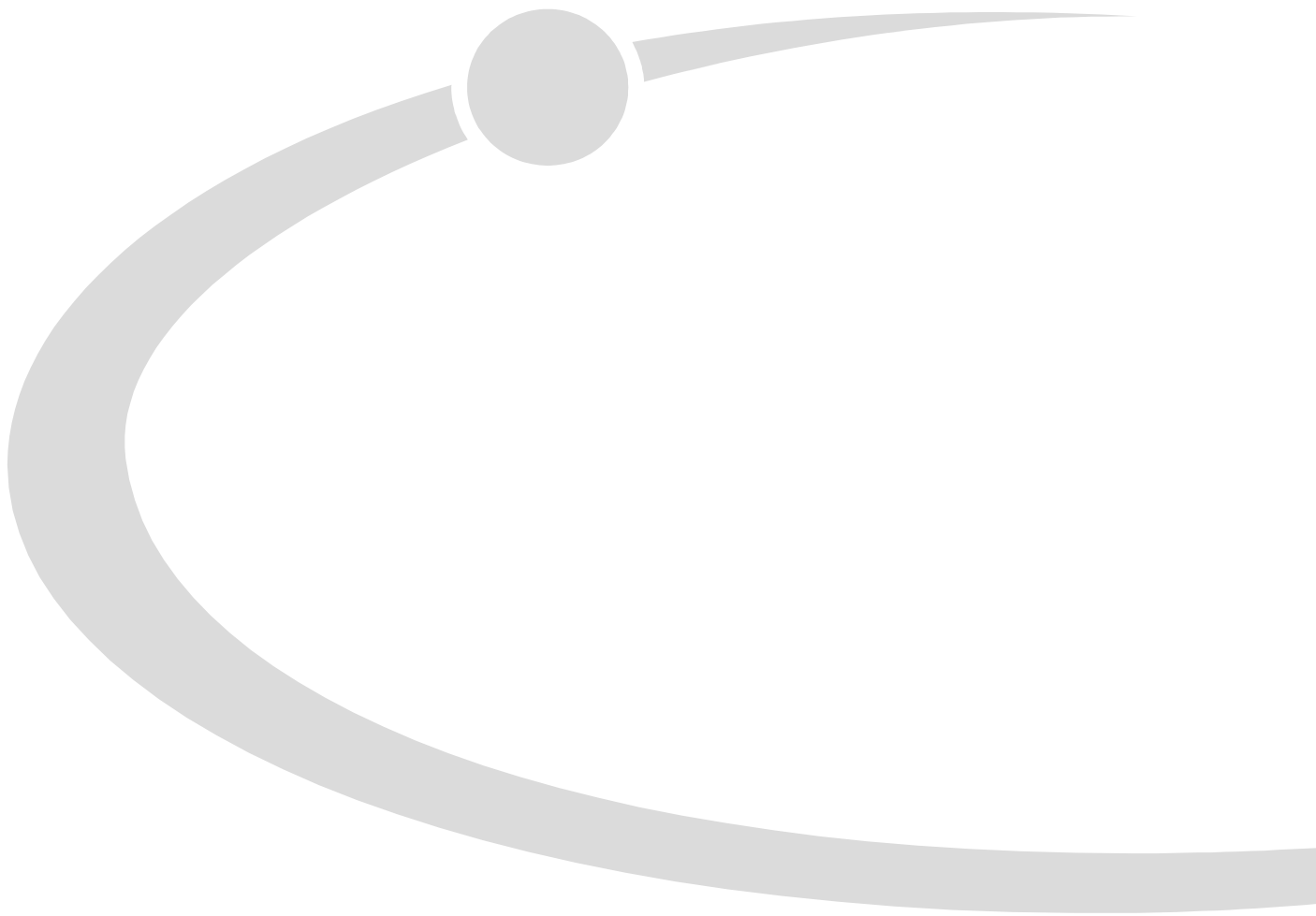
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